



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-05-14
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	gregorio duro	Representative title	ADGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
HFA80A-F2Y	AHF2*UR8ZCA1	A	959	2024-05-14
	Amount	Unit of measure	Unit type	ST ECOPACK grade
	180.00	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	DM01073491	
Package designator	Package size	Number of instances	Shape	
QFP	7x7x1.4	48	Gull wing	
Comment	LQFP 7X7 48L EXPOSED PAD UP. MDF valid for CPs: HFA80A-F2T,HFA80A-F2Y			

QueryList : RoHS Directive 2011/65/EU - 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		True
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		False
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		False
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		False
Exemption Id.	Description	

QueryList : ELV directive : 2000/53/EC amended 2020/363_March 2020		Response
1 - Product(s) meets EU ELV requirements without any exemptions		True
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		False
Exemption Id.	Description	

QueryList : California Prop65 list, dated 17th Nov 2023			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			False
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			True
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.138	dai - leadframe	6322

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				True
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				True
CategoryLevel_Name	CategoryLevel_Threshold	Amount in embedded article / Homogeneous material (mg)	Application - article / Homogeneous material	ppm in article /Homogeneous material



QueryList : Responsible metals sourcing	Response
The component is containing at least one of the following metals : Cobalt , Gold , Tantalum , Tin , Tungsten.	true
The following metals are present is the component :	Cobalt, Gold, Tungsten,

QueryList : Korea Chemical Control Act_ 27 Dec 2017 update	Response
The Product does contain at least one of the substances listed in Chemical Control Act	False

QueryList : China GB 33372-2020 Limit standard for volatile organic compounds content in adhesives - 4 March 2020 application date 1st December 2020	Response
The product contains adhesives identified under GB 33372	False

Stockholm Convention Persistent Organic Pollutants	Response
Product is compliant with Stockholm Convention Persistent Organic Pollutants Annex I	True

QueryList : EUSRR Directive	Response
Product contains hazardous materials listed in EUSRR Annex II	False

PFAS/PTFE Declaration	Response
The product is containing at least one of the following PFAS substance: Polytetrafluoroethylene,Thiophenium, Triphenylsulfonium nonaflate, Trifluoroacetic anhydride	False

BPA Declaration	Response
Product does not contain Bisphenol A (Isopropylidenediphenol)	True

Montreal Protocol	Response
Product does not contain Ozone Depleting Substances based on Annex I to Annex VII of EU REGULATION (EC) No 1005/2009	True

Environmental Protection Agency:Toxic Substances Control Act (TSCA). Section 6(h)	Response
Product does not contain Phenol, isopropylated, phosphate (3:1)	True



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	AHF2'UR&ZCA1									
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die	M-011 Other inorganic materials	18.847	mg	supplier	die	Silicon(Si)	7440-21-3		17.251	mg	915319	95840				
				supplier	metallisation	Copper(Cu)	7440-50-8		1.176	mg	62397	6533				
				supplier	metallisation	Cobalt(Co)	7440-48-4		0.002	mg	106	11				
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.132	mg	7004	733				
				supplier	metallisation	Palladium(Pd)	7440-05-3		0.042	mg	2228	233				
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.001	mg	53	6				
				supplier	metallisation	Tungsten(W)	7440-33-7		0.055	mg	2918	306				
				supplier	passivation	Silicon oxide	7631-86-9		0.188	mg	9975	1044				
				Leadframe	M-004 Copper and its alloys	68.567	mg	supplier	alloy	Copper(Cu)	7440-50-8		65.745	mg	958844	365250
								supplier	alloy	Iron(Fe)	7439-89-6		1.546	mg	22547	8589
supplier	alloy	Iron phosphide	1310-43-6						0.093	mg	1356	517				
supplier	alloy	Zinc(Zn)	7440-66-6						0.081	mg	1181	450				
supplier	metallization	Nickel (Ni)	7440-02-0						1.006	mg	14672	5589				
supplier	metallization	Palladium (Pd)	7440-05-3						0.026	mg	379	144				
supplier	metallization	Gold (Au)	7440-57-5						0.062	mg	904	344				
supplier	metallization	Silver (Ag)	7440-22-4						0.008	mg	117	44				
Die attach	M-011 Other inorganic materials	2.218	mg					supplier	glue	Silver(Ag)	7440-22-4		1.978	mg	891795	10989
								supplier	glue	Isobornyl Methacrylate	7534-94-3		0.166	mg	74842	922
				supplier	glue	Bismaleimide resin	35325-39-4		0.067	mg	30207	372				
				supplier	glue	Epoxyhexylethyltrimethoxysilane	3388-04-3		0.007	mg	3156	39				
Bonding wires	M-004 Copper and its alloys	2.925	mg	supplier	wire	Copper(Cu)	7440-50-8		2.925	mg	1000000	16250				
Bonding wires 2	M-004 Copper and its alloys	2.324	mg	supplier	wire	Copper(Cu)	7440-50-8		2.324	mg	1000000	12911				
Encapsulation	M-011 Other inorganic materials	85.119	mg	supplier	mold compound	Silica vitreous	60676-86-0		69.329	mg	814495	385161				
				supplier	mold compound	Silicon oxide	7631-86-9		6.384	mg	75001	35467				
				supplier	mold compound	Epoxy type resin	25068-38-6		6.384	mg	75001	35467				
				supplier	mold compound	Phenol type resin	29690-82-2		2.554	mg	30005	14189				
				supplier	mold compound	Carbon black	1333-86-4		0.468	mg	5498	2600				